

Research on improving the performance and reliability of next-generation memory and analysis of the Performance and Reliability Mechanisms of GaN High Electron Mobility Transistors

吳重緯 Chung-Wei Wu

NSYSU, PhD Candidate
URL: <https://phys.nsysu.edu.tw/>

URL QR



15:10-16:00 Thu-17/Sep/2026, at 地址: PH2006

Abstract

Resistive random-access memory (RRAM) has attracted considerable attention as a promising non-volatile memory because of its simple structure, fast switching speed, and low power consumption. Meanwhile, GaN high-electron-mobility transistors (HEMTs) are suitable for high-frequency and high-power applications due to their wide bandgap and high electron mobility.

This dissertation investigates the performance and reliability of HfO_2 -based RRAM and p-GaN HEMTs. For RRAM, Ag doping was introduced to reduce the forming voltage and suppress cell-size dependence by facilitating conductive-filament formation. For p-GaN HEMTs, off-state stress caused positive threshold-voltage shift and abnormal subthreshold-swing degradation, which were attributed to non-uniform electron trapping in the AlGaIn region. In addition, low-frequency noise and random telegraph signal analyses were employed to characterize p-GaN/AlGaIn interface defects, showing that stronger interface trapping is closely related to degraded channel conduction and device reliability.



Designed with help from